P/N 95-132I25 JEDEC 132-Position QFP-to-PGA Adapter 0.025 [0.64] Pitch

FEATURES

- Convert surface-mount QFP packages to a 13x13 PGA footprint.
- Reduce costs by using less-expensive QFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for Panelized Form or for mounting of consigned chips.

GENERAL SPECIFICATIONS

- ADAPTOR BODY: FR-4 with 1-oz. Cu traces
- PADS: Bare Cu protected with Entek® by Enthone or immersion white Sn to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: 200µ [5.08µ] Sn/Pb 93/7 per ASTM B579-73 over 100µ [2.54µ] Ni per SAE AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

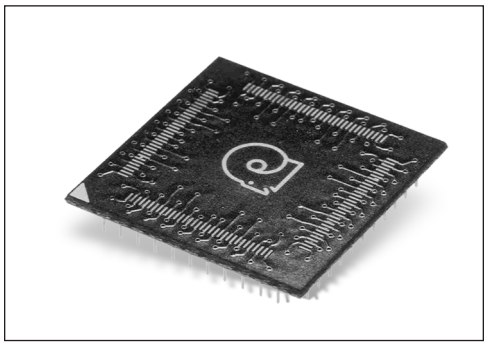
- SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71 ±0.08] dia.
- Will plug into standard PGA socket

ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED

ROW-TO-ROW AND PIN-TO-PIN ±0.003 [±0.08]

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



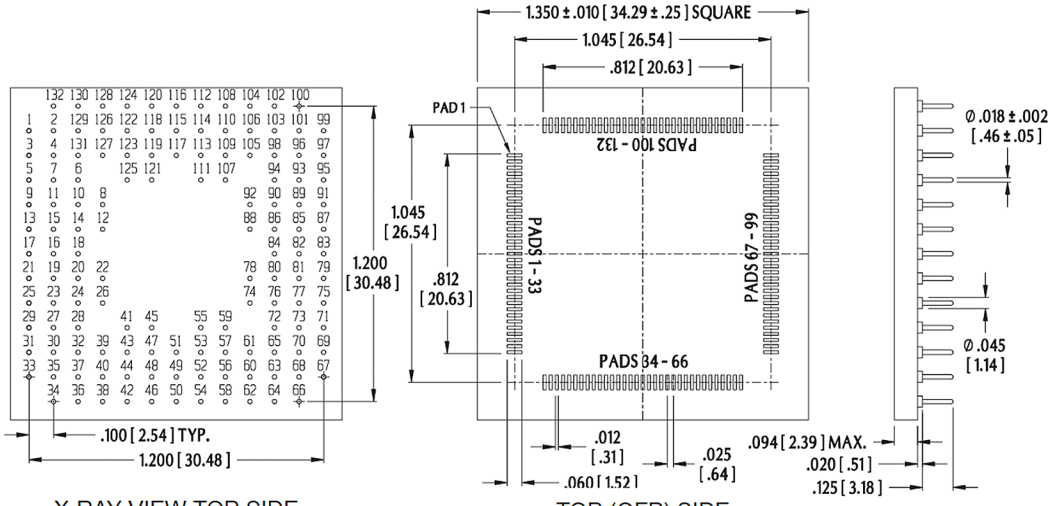
CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE**: Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

P/N 95132125 QFP-to-PGA 13x13 Adapter

P/N 995132125-P QFP-to-PGA 13x13 Panilized Form

P/N 132PGM13072-30 QFP-to-PGA 13x13 Wire Wrap



X-RAY VIEW TOP SIDE
QFP PAD ASSIGNMENT

TOP (QFP) SIDE

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